

PRODUCT SPECIFICATION

PRODUCT NAME: Sesame Seeds

Common Name	Sesame Seeds		
Ingredients	Sesame Seeds		
Microbiological Specifications	Total Plate Count <25 000 cfu per gram Coliforms <100 MPN per gram E Coli <3 MPN per gram Salmonella – Not detected in 35 grams Yeast & Moulds <100 cfu per gram		
Nutritional Panel Information	Nutrition Information Servings per package: (varies depending on package weight) Serving Size: 100 gm		
	Serving Size. 100 gm	Average Quantity per 100 g	
	Engrav	2531kJ	
	Energy Protein	22.2g	
	Fat, total	55.6g	
	- saturated	6.8g	
	Carbohydrate	24g	
	- sugars	0.6g	
	Sodium	24mg	
Genetically modified foods present	GMO Free		
Potential Allergens (product or processing)	Product: Sesame Seed		
Physical Appearance	Coloured – Creamy White Shape- Flat, Oval Texture – smooth Flavour – Characteristic		
Weight(s)	15kg		
Type of Packaging	Paper bag with food grade plastic liner		



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Intended Use	To be consumed by the general population without further processing.		
Standard Packaging for Delivery	In sealed packaging		
Recommended Storage Conditions	Keep cool and dry and away from direct sunlight. Keep away from other food that may harbour insects and strong odours.		
Shelf Life (packaged product)	12 months under recommended storage conditions		
Country of Origin (List % if >1 country)	India		
Where Sold	Retail shops, manufactures, supermarkets, distributors, food service		
Target Groups	General population		
Customer Preparation	None required		
Sensitive Populations	Sesame Seed		
Labelling Requirements	Labelled in accordance with the FSANZ Food Standards Code		
Delivery Methods	Delivery vehicle at ambient temperature stored separately from chemicals or other substances that may present potential for cross contamination.		
Special Distribution Controls (if any)	Nil		
Foreign Materials	Shell, husk, stone, stick, embedded shell, plastic, metal and glass		
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Reviewed By: Rana Colosimo Sign: Rana Colosimo Date: 14.01.2021